

ICCON Connector Family Overview

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ICCON Connectors

Product Overview

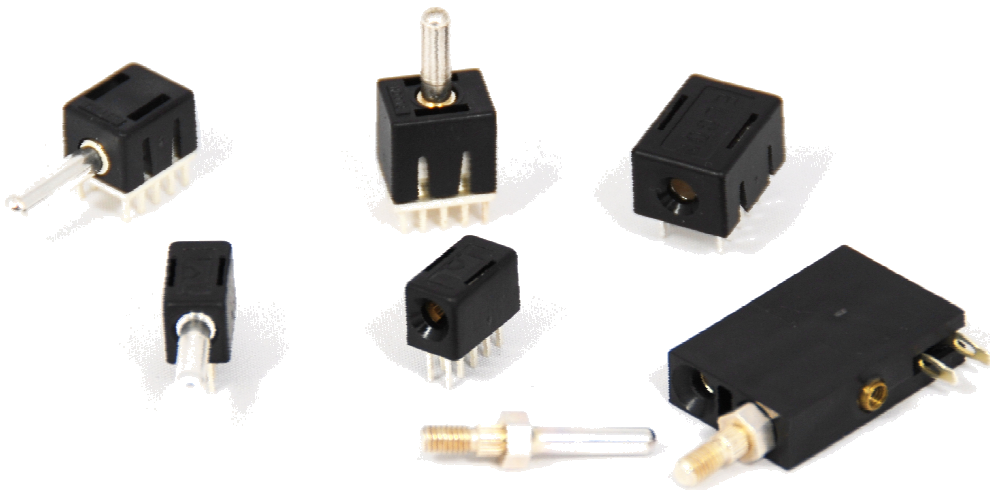
- Standard ICCON connectors
- SLIMLINE ICCON connectors
- Stacked ICCON connectors

Product Highlights

- High performance contact
- Optional locking feature
- Support for multiple mounting styles
- Mating with discrete contacts

Product Facts

- 35A current rating
- True compliant press-fit and solder tails
- Pin locking feature option
- Standard DIP footprint
- Insulator rated at 105°C, UL 94V-0
- Meets safety regulatory requirements
- #8 AWG wire size
- Parallel and perpendicular pin/sockets
- Sequencing capability
- For 0.062" to 0.125" boards
(1.57 mm ~ 3.18 mm)

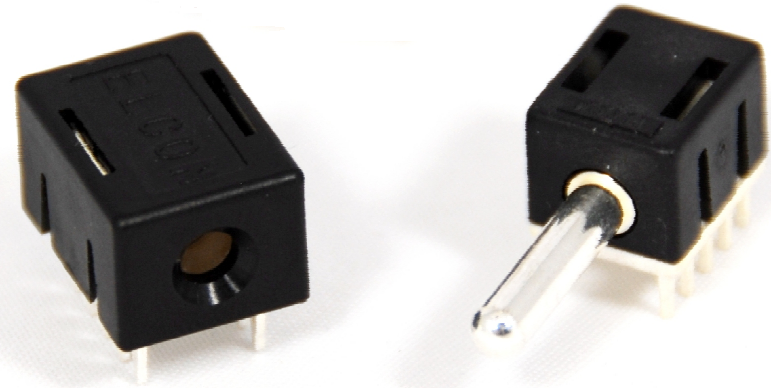




 Always EU RoHS/ELV Compliant

Standard ICCON Connectors

Product Overview

- Provides a reliable high current power interconnection
- Quick connect / disconnect functionality for space constrained motherboard-daughterboard, cable-board and board-busbar power delivery applications.
- Standard DIP footprint .300 x .100



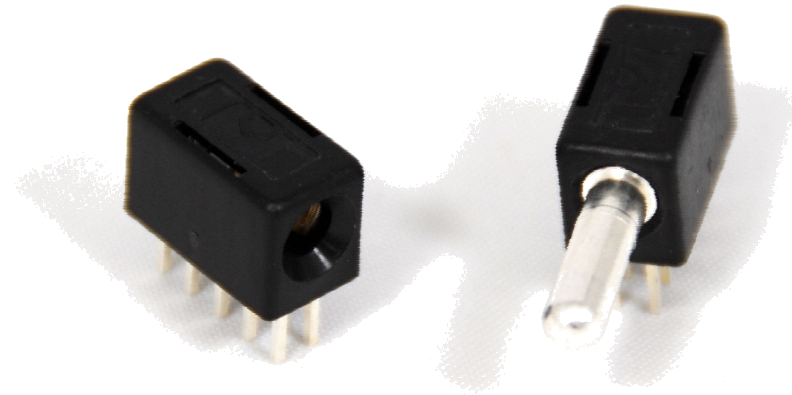
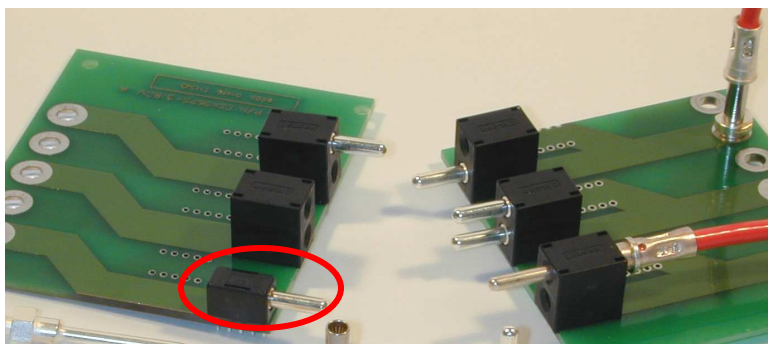
Standard ICCON Connector Options	
Receptacle 	Right angle or vertical
Pin 	Right angle or vertical, multiple lengths available
Mating options	Coplanar, mezzanine, right angle
PCB termination	Solder tail or compliant pin



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SLIMLINE ICCON Connectors

Product Overview

- Footprint close to 30% smaller than the standard ICCON connectors
- Integrates more component in less board real estate, providing substantial space savings compared to connectors of this type in the same performance range
- SLIMLINE ICCON connector footprint .100 x .100



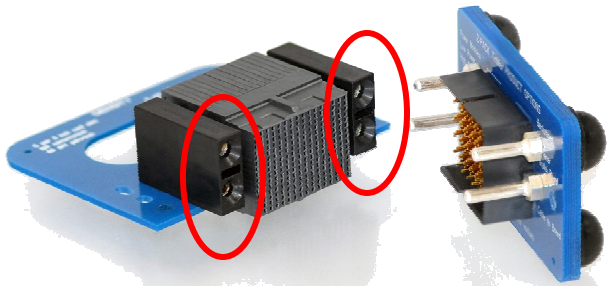
SLIMLINE ICCON Connector Part Numbers	
Receptacle 	Right angle
Pin 	Right angle, multiple lengths available
Mating options	Right angle
PCB termination	Solder tail or compliant pin

 Always EU RoHS/ELV Compliant

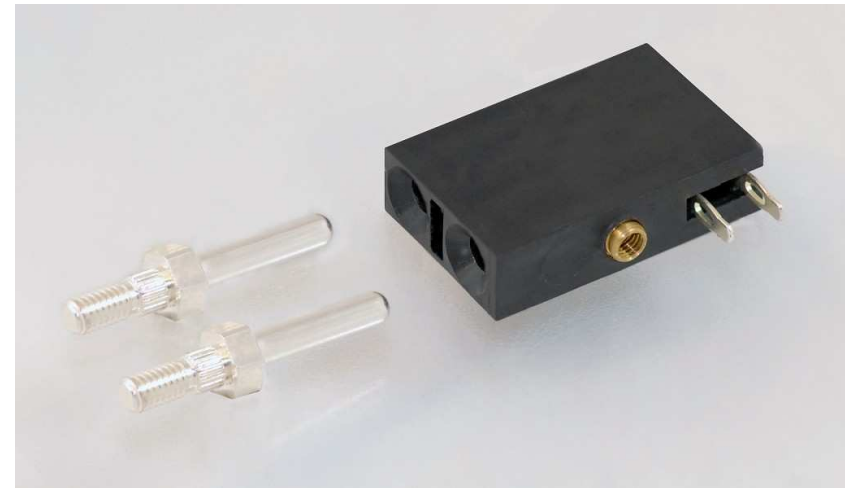
Stacked ICCON Connectors



Product Overview

- Very high current density – Up to 200 Amps per inch
- Occupies less pcb edge space than separate ICCON power and guide modules
- Designed to compliment Z-PACK TinMan connector and other backplane connectors offered by TE
- Right-angle connector to mate motherboard-daughterboard power distribution systems



*Stacked ICCON connector shown with Z-PACK TinMan backplane connector



Stacked ICCON Connector Part Numbers	
Receptacle 	Stacked, right angle
Pin 	Ground, power, mate-first, multiple lengths available
PCB termination	Compliant pin

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ICCON Connectors

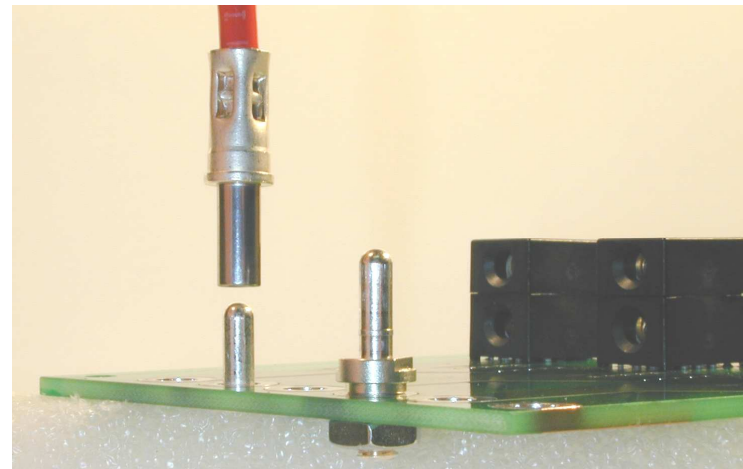
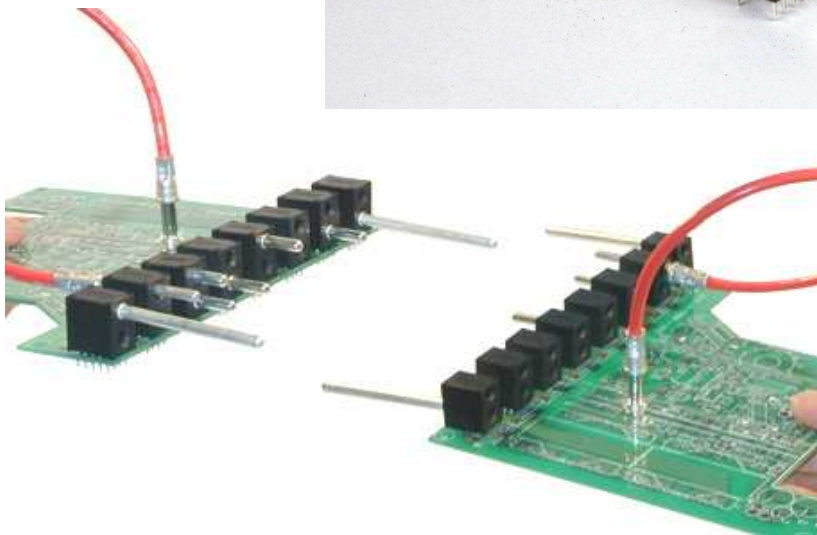
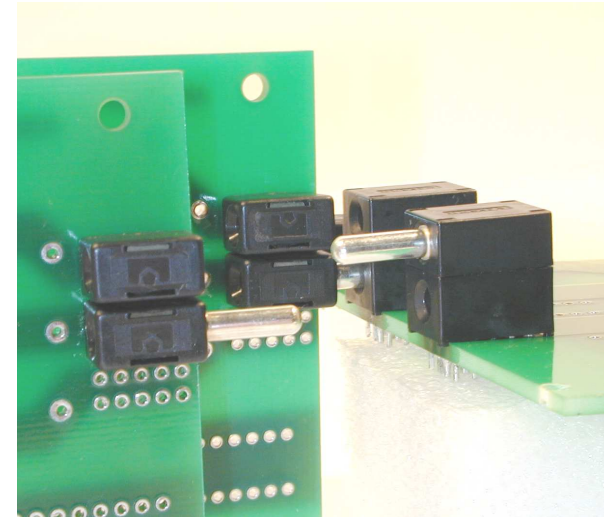
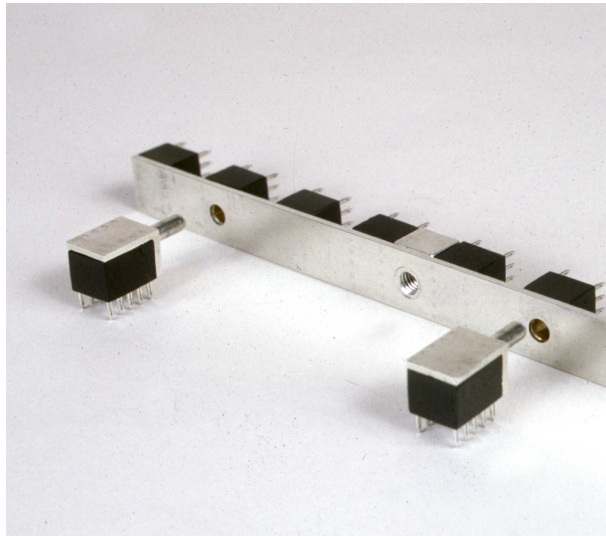
Typical Product Applications

- Power distribution
- Board-to-board interconnection
- Board-to-busbar interconnection
- Board-to-wire interconnection
- High-density power designs
- Board stacking

ICCON connectors provide a reliable high current power interconnection with quick connect / disconnect function for space constrained motherboard-daughterboard, cable-board and board-busbar power delivery applications.

ICCON Connectors

Sample Application Photos



ICCON Connectors

More Information

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